

GSM6903S

60V P-Channel MOSFETs

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

Features

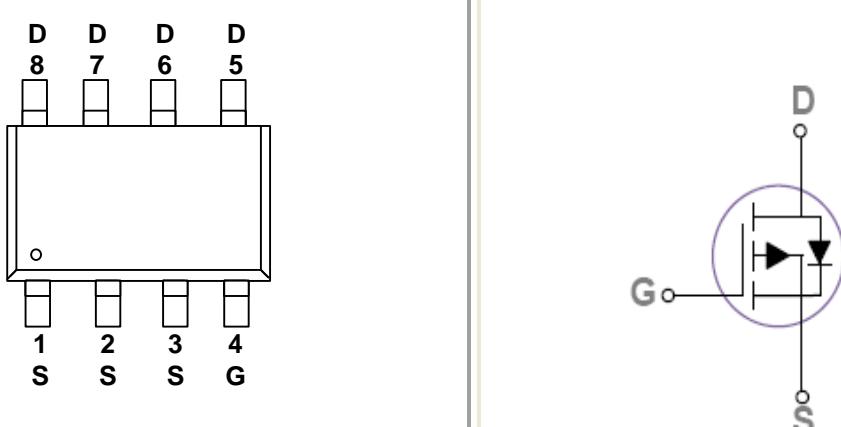
- -60V, -8.5A, $R_{DS(ON)}=30m\Omega$ @ $V_{GS}=-10V$
- Fast switching
- Suit for -4.5V Gate Drive Applications
- Green Device Available

Applications

- POL Applications
- Load Switch
- LED Application

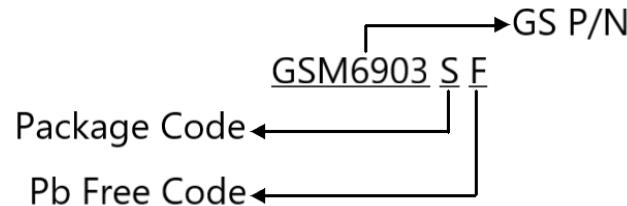
Packages & Pin Assignments

| GSM6903SF (SOP-8) | | |
|-------------------|--------|-------------|
| Pin No | Symbol | Description |
| 1,2,3 | S | Source |
| 4 | G | Gate |
| 5,6,7,8 | D | Drain |



GSM6903S

Ordering Information



| Part Number | Package | Quantity |
|-------------|---------|----------|
| GSM6903SF | SOP-8 | 4000pcs |

Marking Information

The diagram shows the marking information for the device. It consists of two parts: 'Part Number' (DS6903) and 'GS Code' (XWMMMM).

Absolute Maximum Ratings

T_c=25°C Unless otherwise noted

| Symbol | Parameter | Typical | Unit |
|------------------|--|--|--------------|
| V _{DS} | Drain-Source Voltage | -60 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D | Continuous Drain Current | T _c =25°C T _c =70°C | -8.5 -5.4 |
| I _{DM} | Pulsed Drain Current ¹ | -34 | A |
| P _D | Power Dissipation | 4.1 | W |
| | Power Dissipation-Derate above 25°C | 0.033 | W/°C |
| T _J | Operating Junction Temperature Range | -55 to +150 | °C |
| T _{STG} | Storage Temperature Range | -55 to +150 | °C |
| R _{θJA} | Thermal Resistance-Junction to Ambient | 62 | °C/W |
| R _{θJC} | Thermal Resistance-Junction to Case | 30 | °C/W |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

Electrical Characteristics

T_J=25°C Unless otherwise noted

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------------|-----------------------------------|--|------|------|------|------|
| Static | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | -60 | --- | --- | V |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | -1.0 | -1.6 | -2.5 | V |
| I _{GSS} | Gate-Source Leakage Current | V _{DS} =0V, V _{GS} =±20V | --- | --- | ±100 | nA |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =-60V, V _{GS} =0V T _J =25°C | --- | --- | -1 | μA |
| | | V _{DS} =-48V, V _{GS} =0V, T _J =125°C | --- | --- | -10 | |
| I _S | Continuous Source Current | V _G =V _D =0V, Force Current | --- | --- | -8.5 | A |
| I _{SM} | Pulsed Source Current | | --- | --- | -17 | |
| R _{DS(on)} | Drain-Source On-Resistance | V _{GS} =10V, I _D =-1.8A | --- | 23 | 30 | mΩ |
| | | V _{GS} =4.5V, I _D =-1.5A, | --- | 28 | 40 | |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V, I _S =-1A | --- | --- | -1 | V |
| g _{fs} | Forward Transconductance | V _{DS} =-10V, I _D =-3A | --- | 18 | --- | S |
| Dynamic | | | | | | |
| Q _g | Total Gate Charge ^{2,3} | V _{DS} =-30V, V _{GS} =-10V, I _D =-5A | --- | 43.8 | 88 | nC |
| Q _{gs} | Gate-Source Charge ^{2,3} | | --- | 4.6 | 9 | |
| Q _{gd} | Gate-Drain Charge ^{2,3} | | --- | 8.3 | 17 | |
| C _{iss} | Input Capacitance | V _{DS} =-25V, V _{GS} =0V, f=1MHz | --- | 2595 | 3900 | pF |
| C _{oss} | Output Capacitance | | --- | 162 | 240 | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 115 | 170 | |
| t _{d(on)} | Turn-On Time ^{2,3} | | --- | 25 | 50 | |
| t _r | Rise Time ^{2,3} | V _{DD} =-30V, I _D =-1A, V _{GS} =-10V, R _G =6Ω | --- | 13.8 | 28 | ns |
| t _{d(off)} | Turn-Off Time ^{2,3} | | --- | 148 | 290 | |
| t _f | Fall Time ^{2,3} | | --- | 51 | 100 | |

Note :

2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.

3. Essentially independent of operating temperature.

Typical Performance Characteristics

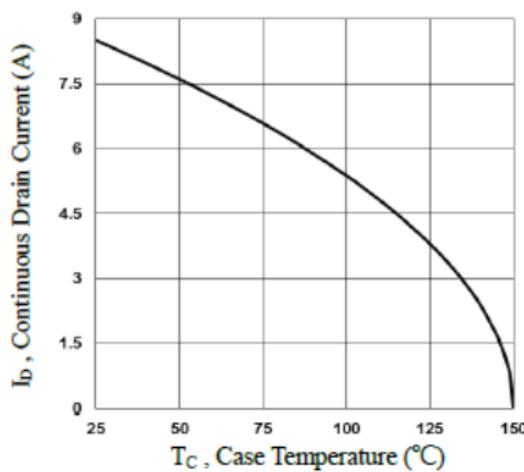


Fig.1 Continuous Drain Current vs. T_c

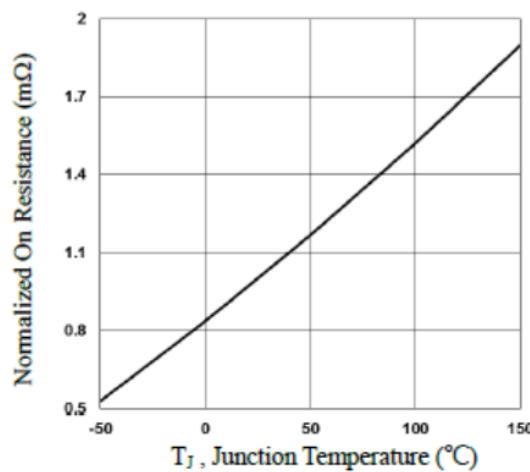


Fig.2 Normalized RDS(on) vs. T_j

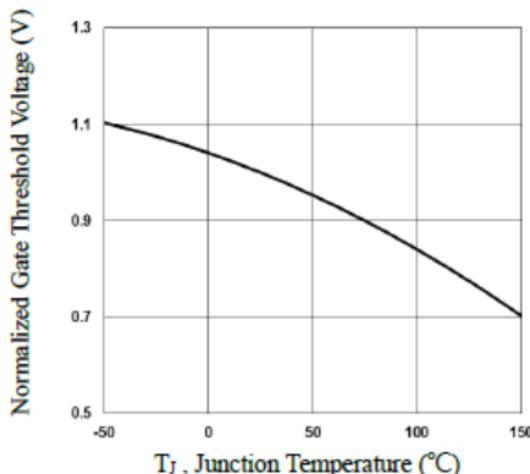


Fig.3 Normalized V_{th} vs. T_j

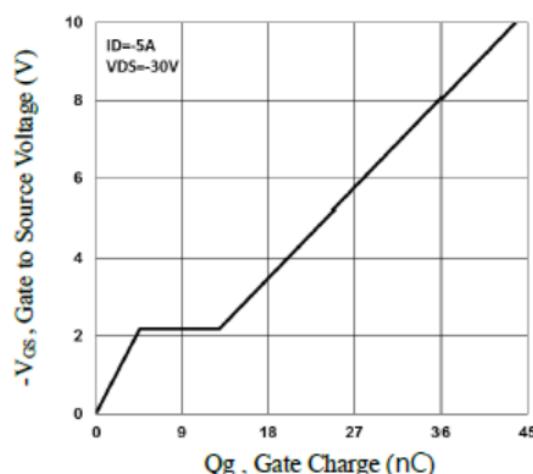


Fig.4 Gate Charge Waveform

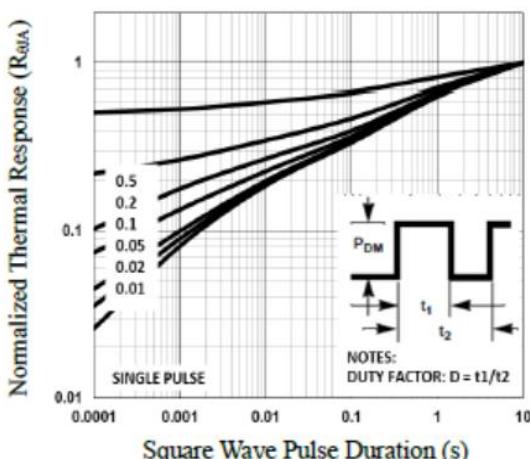


Fig.5 Normalized Transient Impedance

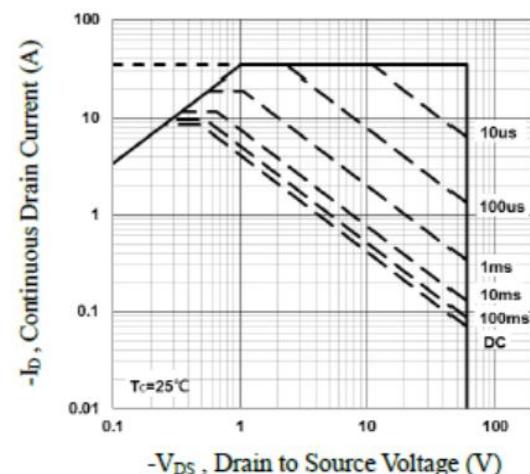


Fig.6 Maximum Safe Operation Area

Typical Performance Characteristics(continue)

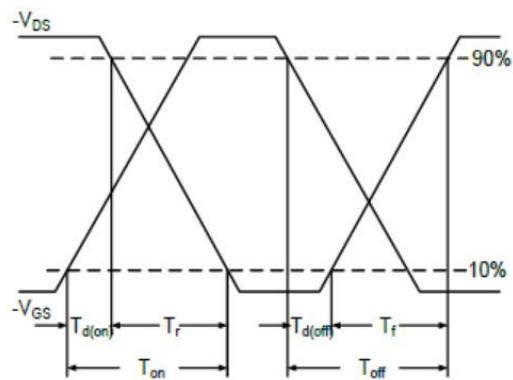


Fig.7 Switching Time Waveform

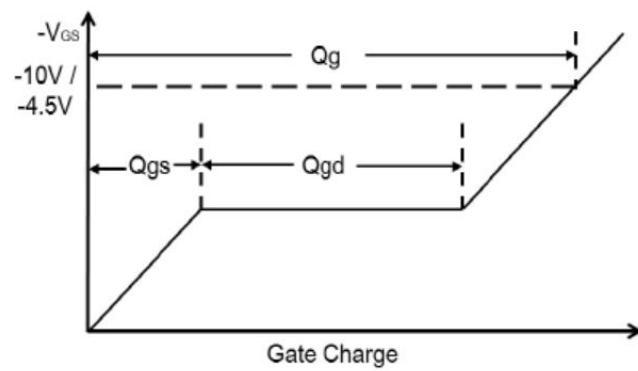
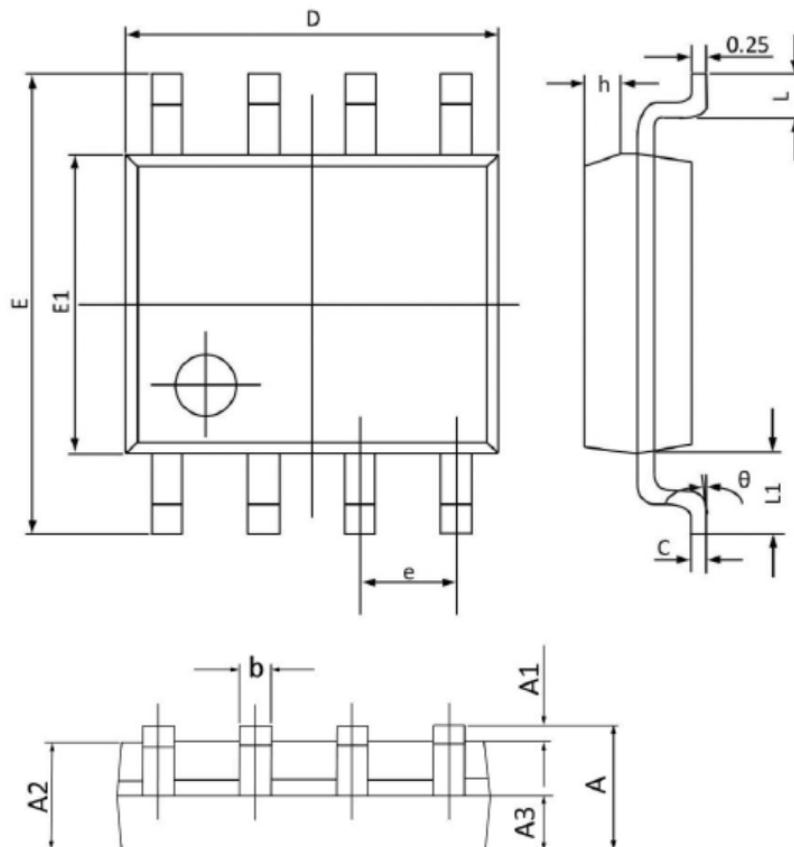


Fig.8 Gate Charge Waveform

Package Dimension

SOP-8



Dimensions

| SYMBOL | Millimeters | | Inches | |
|--------|-------------|-------|------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.350 | 1.750 | 0.053 | 0.068 |
| A1 | 0.100 | 0.250 | 0.004 | 0.009 |
| A2 | 1.300 | 1.500 | 0.052 | 0.059 |
| A3 | 0.600 | 0.700 | 0.024 | 0.027 |
| b | 0.390 | 0.480 | 0.016 | 0.018 |
| c | 0.210 | 0.260 | 0.009 | 0.010 |
| D | 4.700 | 5.100 | 0.186 | 0.200 |
| E | 5.800 | 6.200 | 0.229 | 0.244 |
| E1 | 3.700 | 4.100 | 0.146 | 0.161 |
| e | 1.270(BSC) | | 0.050(BSC) | |
| h | 0.250 | 0.500 | 0.010 | 0.019 |
| L | 0.500 | 0.800 | 0.019 | 0.031 |
| L1 | 1.050(BSC) | | 0.041(BSC) | |
| θ | 0° | 8° | 0° | 8° |

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CONTACT US

GS Headquarter



4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd Neihu District Taipei City 114, Taiwan (R.O.C)



886-2-2657-9980



886-2-2657-3630



sales_twn@gs-power.com

RD Division



824 Bolton Drive Milpitas. CA. 95035



1-408-457-0587